

2019 2nd International Conference on Materials Design and Applications (ICMDA 2019)

Tokyo Institute of Technology, Japan

April 13-15, 2019



Conference Introduction

2019 2nd International Conference on Materials Design and Applications (ICMDA 2019: <http://www.icmda.org/>) will be held in Tokyo Institute of Technology, Japan during April 13-15, 2019.

It provides an opportunity for the delegates to meet, interact and exchange new ideas in the various areas of materials design and applications. ICMDA 2019 aims to proclaim knowledge and share new ideas among the professionals, industrialists and students from research areas of materials design and applications to share their research experiences and indulge in interactive discussions and special sessions at the event.

Good News

1. Publication

Option One: **Materials Science Forum** (ISSN: 1662-9752), which can be indexed by **EI Compendex**, **Scopus** and so on. For online and index information: <http://www.ttp.net/0255-5476.html>



Option Two: **International Journal of Materials, Mechanics and Manufacturing** (IJMMM, ISSN: 1793-8198), which can be indexed by EI (INSPEC, IET), Chemical Abstracts Services (CAS), ProQuest, Crossref and so on.



2. Famous professors as Speakers

Prof. Kazushi Kinbara, Tokyo Institute of Technology, Japan;

Prof. Takashige Omatsu, Chiba University, Japan;

Prof. Hongqi Sun, Edith Cowan University, Australia;

Prof. Xiaozhong Zhang, Tsinghua University, China.

3. Academic Visit

There will be a half-day academic visit in Tokyo Institute of Technology and half-day tour in Tokyo on April 15, 2019.

Important Dates

Paper Submission	February 10, 2019
Notification of Acceptance	March 01, 2019
Authors' Registration	Before March 15, 2019
Listeners' Registration	Before March 25, 2019
Conference Dates	April 13-14, 2019
Academic Visit	April 15, 2019

Call for Papers

Topics of interest for submission include, but are not limited to: **Materials Properties, Measuring Methods and Applications** ---Ductility, Crack Resistance, Fatigue, Creep-resistance, Fracture Mechanics, Mechanical Properties, Electrical Properties, Magnetic Properties, Corrosion, Erosion, Wear Resistance, Non-Destructive Testing, Reliability Assessment, Toxicity, Working Properties of Materials and Products, Large Scale Applications, Electronics Applications; **Materials Science and Materials Processing Technology**---Composite, Micro/Nano materials, Iron & Steel, Ceramics, Metal, Alloy Material, Polymer, Optical / Electrical / Magnetic Materials, Materials Physics and Chemistry, Building Materials, Energy Materials, Environmental-Friendly Materials, Biological Material, Chemical Materials, Thin Films, Seismic materials; **Materials Analyses and Modeling**---Electron Microscopy, Image Analysis, X-ray Phase Analysis, Metallography, Computational Material Science, Numerical Techniques, Materials Design, Materials and Engineering Databases, Expert Systems, Artificial Intelligence Methods, Non-Destructive Testing, Reliability Assessment and Other related fields. (For more information, please visit <http://www.icmda.org/cfp.html>)

Submission Methods

- Electronic Submission Method:
<http://confsys.iconf.org/submission/icmda2019>
- Conference Email Address: icmda@cbees.net

Contact us

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